

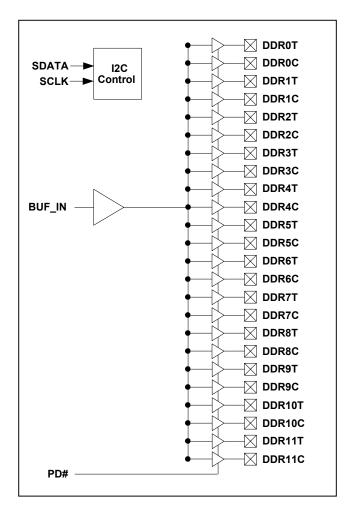
PLL103-02

DDR SDRAM Buffer for Desktop PCs with 4 DDR DIMMS

FEATURES

- Generates 24 output buffers from one input.
- Supports up to four DDR DIMMS.
- Supports 266MHz DDR SDRAM.
- One additional output for feedback.
- Less than 5ns delay.
- Skew between any outputs is less than 100 ps.
- 2.5V Supply range.
- Enhanced DDR Output Drive selected by I2C.
- Available in 48 pin SSOP.

BLOCK DIAGRAM



PIN CONFIGURATION

| | | | | 1 |
|----------|----|------------|----|--------|
| FBOUT 🖂 | 1 | \bigcirc | 48 | □ N/C |
| VDD2.5 🖂 | 2 | | 47 | UDD2.5 |
| GND 🗆 | 3 | | 46 | |
| DDR0T | 4 | | 45 | DDR11T |
| DDR0C | 5 | | 44 | DDR11C |
| DDR1T | 6 | | 43 | DDR10T |
| DDR1C | 7 | | 42 | DDR10C |
| VDD2.5 🖂 | 8 | | 41 | UDD2.5 |
| GND 🗆 | 9 | | 40 | 🗖 GND |
| DDR2T | 10 | P | 39 | DDR9T |
| DDR2C | 11 | | 38 | DDR9C |
| VDD2.5 | 12 | Z | 37 | UDD2.5 |
| BUF_IN | 13 | 2 | 36 | D PD# |
| GND 🖂 | 14 | 03 | 35 | |
| DDR3T 🖂 | 15 | , w | 34 | DDR8T |
| DDR3C | 16 | 6 | 33 | DDR8C |
| VDD2.5 | 17 | N | 32 | UDD2.5 |
| GND 🗆 | 18 | | 31 | |
| DDR4T | 19 | | 30 | DDR7T |
| DDR4C | 20 | | 29 | DDR7C |
| DDR5T 🖂 | 21 | | 28 | DDR6T |
| DDR5C | 22 | | 27 | DDR6C |
| VDD2.5 | 23 | | 26 | 🗆 GND |
| SDATA 🖂 | 24 | | 25 | SCLK |
| | | | | 1 |

Note: #: Active Low

DESCRIPTION

The PLL103-02 is designed as a 2.5V buffer to distribute high-speed clocks in PC applications. The device has 24 outputs. These outputs can be configured to support four unbuffered DDR DIMMS. The PLL103-02 can be used in conjunction with a clock synthesizer for the VIA Pro 266 chipset. The PLL103-02 also has an I2C interface, which can enable or disable each output clock. When powered up, all output clocks are enabled (have internal pull ups).



PIN DESCRIPTIONS

| Name | Number | Туре | Description |
|------------|---|------|--|
| FBOUT | 1 | 0 | Feedback clock for chipset. |
| BUF_IN | 13 | I | Reference input from chipset. |
| PD | 36 | I | Power Down Control input. When low, it will tri-state all outputs. |
| N/C | 48 | | Not connected. |
| DDR[0:11]T | 4,6,10,15,19, 21,28,30,34, 39,43,45 | 0 | These outputs provide True copies of BUF_IN. |
| DDR[0:11]C | 5,7,11,16,20, 22,27,29,33, 38,42,44 | 0 | These outputs provide complementary copies of BUF_IN. |
| VDD2.5 | 2,8,12,17,23, 32,37,41,47 | Р | 2.5V power supply. |
| GND | 3,9,14,18,26, 31,35,40,46 | Р | Ground. |



I2C BUS CONFIGURATION SETTING

| Address Assignment | A6 1 | A5 1 | A4 0 | A3 1 | A2 0 | A1 0 | A0 1 | R/W | | |
|-------------------------------|--|---|--|---|---|--|---|---|---------------------------------|--|
| Slave Receiver/Transmitter | Provid | des both s | lave write | and readb | oack functi | onality | | | | |
| Data Transfer Rate | Stand | tandard mode at 100kbits/s | | | | | | | | |
| Data Protocol | bytes must termir addre Follov Coun | must be a be followe hate the trans ss and a w ving the ac t Byte mu | ccessed i d by 1 ack ansfer. Th vrite cond cknowledg st be sen be read l | n sequenti knowledge e write or ition (0xD2 je of this a t by the n | ial order fr bit. A byte read block 2) or a read ddress by naster but | om lowest e transferr c both beg d conditior te, in Writ ignored b | to highest ed without ins with the n (0xD3). e Mode: th y the slave | acknowledge e master sene e Command , in Read Mo | oyte transferred ed bit will | |

I2C CONTROL REGISTERS

1. BYTE 6: Outputs Register (1=Enable, 0=Disable)

| Bit | Pin# | Default | Description |
|-------|--------|---------|--------------------------------------|
| Bit 7 | 48 | 1 | Reserved |
| Bit 6 | - | 0 | Reserved |
| Bit 5 | - | 0 | Enhanced DDR Drive. 1 = Enhanced 25% |
| Bit 4 | - | 0 | Reserved |
| Bit 3 | 45, 44 | 1 | DDR11T, DDR11C |
| Bit 2 | 43, 42 | 1 | DDR10T, DDR10C |
| Bit 1 | 39, 38 | 1 | DDR9T, DDR9C |
| Bit 0 | 34, 33 | 1 | DDR8T, DDR8C |

2. BYTE 7: Outputs Register (1=Enable, 0=Disable)

| Bit | Pin# | Default | Description |
|-------|--------|---------|--------------|
| Bit 7 | 30, 29 | 1 | DDR7T, DDR7C |
| Bit 6 | 28, 27 | 1 | DDR6T, DDR6C |
| Bit 5 | 21, 22 | 1 | DDR5T, DDR5C |
| Bit 4 | 19, 20 | 1 | DDR4T, DDR4C |
| Bit 3 | 15, 16 | 1 | DDR3T, DDR3C |
| Bit 2 | 10, 11 | 1 | DDR2T, DDR2C |
| Bit 1 | 6, 7 | 1 | DDR1T, DDR1C |
| Bit 0 | 4, 5 | 1 | DDR0T, DDR0C |



ELECTRICAL SPECIFICATIONS

1. Absolute Maximum Ratings

| PARAMETERS | SYMBOL | MIN. | MAX. | UNITS |
|-----------------------------------|----------------|----------------------|----------------------|-------|
| Supply Voltage | Vdd | | 4.6 | V |
| Input Voltage, dc | V ₁ | V _{SS} -0.5 | V_{DD} +0.5 | V |
| Output Voltage, dc | Vo | Vss-0.5 | V _{DD} +0.5 | V |
| Storage Temperature | Ts | -65 | 150 | °C |
| Ambient Operating Temperature* | TA | -40 | 85 | °C |
| Junction Temperature | TJ | | 125 | °C |
| Lead Temperature (soldering, 10s) | | | 260 | °C |
| ESD Protection, Human Body Model | | | 2 | kV |

Exposure of the device under conditions beyond the limits specified by Maximum Ratings for extended periods may cause permanent damage to the device and affect product reliability. These conditions represent a stress rating only, and functional operations of the device at these or any other conditions above the operational limits noted in this specification is not implied.

* Note: Operating Temperature is guaranteed by design for all parts (COMMERCIAL and INDUSTRIAL), but tested for COMMERCIAL grade only.

2. Operating Conditions

| PARAMETERS | SYMBOL | MIN. | MAX. | UNITS |
|--------------------|--------------------|-------|-------|-------|
| Supply Voltage | V _{DD2.5} | 2.375 | 2.625 | V |
| Input Capacitance | CIN | | 5 | pF |
| Output Capacitance | Соит | | 6 | pF |

3. Electrical Specifications

| PARAMETERS | SYMBOL | CONDITIONS | MIN. | TYP. | MAX. | UNITS |
|------------------------|-----------------|---------------------------|---------|------|----------------------|-------|
| Input High Voltage | VIH | All Inputs except I2C | 2.0 | | V _{DD} +0.3 | V |
| Input Low Voltage | VIL | All inputs except I2C | Vss-0.3 | | 0.8 | V |
| Input High Current | Іін | $V_{IN} = V_{DD}$ | | | TBM | uA |
| Input Low Current | IIL | V _{IN} = 0 | | | TBM | uA |
| Output High Voltage | V _{OH} | IOL = -12mA, VDD = 2.375V | 1.7 | | | V |
| Output Low Voltage | Vol | IOL = 12mA, VDD = 2.375V | | | 0.6 | V |
| Output High Current | Іон | VDD = 2.375V, VOUT=1V | -18 | -32 | | mA |
| Output Low Current | lol | VDD = 2.375V, VOUT=1.2V | 26 | 35 | | mA |

Note: TBM: To be measured



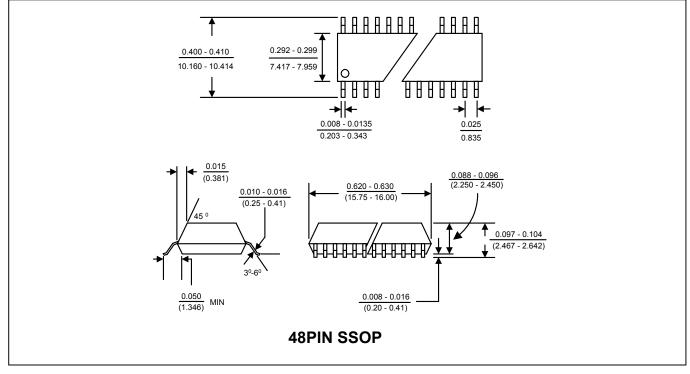
3. Electrical Specifications (Continued)

| PARAMETERS | SYMBOL | CONDITIONS | MIN. | TYP. | MAX. | UNITS |
|-----------------------------|------------------|----------------------------|-----------------|-------|-----------------|-------|
| Supply Current | I _{DDS} | PD = 0 | | | TBM | mA |
| Output Crossing Voltage | Voc | | (VDD/2) -0.1 | VDD/2 | (VDD/2)+ 0.1 | V |
| Output Voltage Swing | Vouт | | 1.1 | | VDD-0.4 | V |
| Duty Cycle | DT | Measured @ 1.5V | 45 | 50 | 55 | % |
| Max. Operating Frequency | | | 66 | | 170 | MHz |
| Rising Edge Rate | Tor | Measured @ 0.4V ~ 2.4V | 1.0 | 1.5 | 2.0 | V/ns |
| Falling Edge Rate | Tof | Measured @ 2.4V ~ 0.4V | 1.0 | 1.5 | 2.0 | V/ns |
| Clock Skew(pin to pin) | Тѕкеѡ | All outputs equally loaded | | | 100 | ps |
| Stabilization Time | T _{ST} | | | | 0.1 | ms |

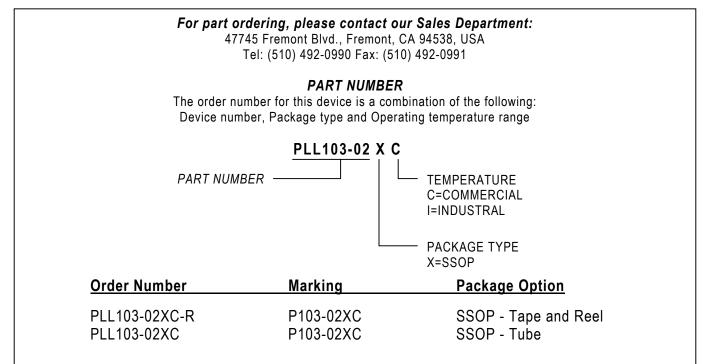
Note: TBM: To be measured



PACKAGE INFORMATION



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